

ABSTRACT

An integrated circuit power distribution system and method is provided. The integrated circuit comprises a semiconductor die that includes at least one pair of bond pads having a single bond wire connected thereto such that each bond pad of the pair of bond pads has only one bond wire end connected thereto. A first bond pad of the pair of bond pads is located in an internal portion of the semiconductor die. A first wire having a first end and a second end is electrically connected between the pair of bond pads.

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